PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	NUNC PRO TUNC ASSIGNMENT
EFFECTIVE DATE:	12/09/1994

CONVEYING PARTY DATA

Name	Execution Date
Francisca Tung	07/01/2011

RECEIVING PARTY DATA

Name:	VLSI Technology, Inc.
Street Address:	1109 McKay Drive
City:	San Jose
State/Country:	CALIFORNIA
Postal Code:	95131

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	5587336

CORRESPONDENCE DATA

Fax Number: (408)474-9082

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Address Line 2: NXP Semiconductors, IP&L
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NAME OF SUBMITTER: David L. Schaeffer

Total Attachments: 1

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PATENT REEL: 026568 FRAME: 0491

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\$40.00

NUNC PRO TUNC ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, I, as the below named Assignor, hereby sell, and assign, and transfer, nunc pro tune effective December 9, 1994, my entire and exclusive right, title, and interest in the following to VLSI TECHNOLOGY, INC., having a place of business at 1109 McKay Drive, San Jose, California 95131, United States, its successors, assigns, and legal representatives, including any nominees (collectively "the Assignee"):

my invention relating to "BUMP FORMATION ON YIELDED SEMICONDUCTORS DIES", for which U.S. Patent No. 5,587,336 was granted on December 24, 1996, (based upon U.S. Patent Application No. 08/353,022, filed on December 9, 1994); and

all rights in and to said patent, and all United States, foreign and international patent applications associated therewith, based thereon, or claiming priority therefrom including, but not limited to, any and all provisionals, non-provisionals, divisions, continuations, continuations-in-part, reexaminations, reissues, and extensions thereof, and the right to claim priority thereto, and the entire and exclusive right, title, and interest in and to any and all patents granted on these applications.

I further confirm that, as of **December 9**, 1994, I had authorized and requested the Patent Office officials in the United States and in any and all foreign countries to issue any and all Letters Patent when granted, solely to VLSI TECHNOLOGY, INC. for its sole use, and that of its successors, assigns, and legal representatives.

I further confirm that, as of December 9, 1994, I had covenanted and agreed and continue to covenant and agree to provide my cooperation to enable the Assignee to enjoy the foregoing right, title, and interest to the fullest extent. Upon request at the expense of the Assignee, I agreed and agree to execute all papers, take all rightful oaths, testify in all legal proceedings including patent prosecutional actions and infringement actions, and do all other such acts which may be necessary, desirable, or convenient for securing and maintaining patents on the foregoing invention or for perfecting title thereto in the Assignee.

I also hereby confirm that, as of **December 9**, 1994. I had transferred unto the Assignee, its successors, legal representatives and assigns, all claims for damages by reason of past infringement of any patents based in whole or part upon said application, the right to sue for and collect the same for their own use and for the use and enjoyment of their successors, legal representatives or other assigns and do hereby assign and set over unto Assignee, its successors and assigns, nunc pro tune effective December 9, 1994, all such claims and rights.

I certify that I have the full right to convey the above rights.

(sign name here)

(print name here)

Assignor